

# UP SuperServer SYS-111E-WR

1U UP WIO with 10 hot-swap 2.5" NVMe/SAS/SATA bays and 3 PCIe 5.0 slots



More details here

## Key Applications

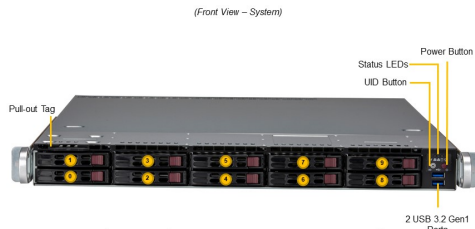
Virtualization, Cloud Computing, Data Center Optimized, Database/Storage, Entry GPU server,

## Key Features

- Single Socket E (LGA-4677) 4th/5th Gen Intel® Xeon® Scalable processors. Up to 300W TDP;
- Intel® C741 Chipset;
- 8 DIMMs; Supports 3DS DDR5 RDIMM. Up to 5600 MHz;
- Onboard 1G LAN ports (Intel® i210), 1 dedicated IPMI LAN;
- 10x front hot-swap 2.5" SATA3 drive bays (Optional all 10 hybrid Gen5 NVMe), SAS3 with additional SAS controller card;
- Redundant Now Titanium 860W Power Supplies;

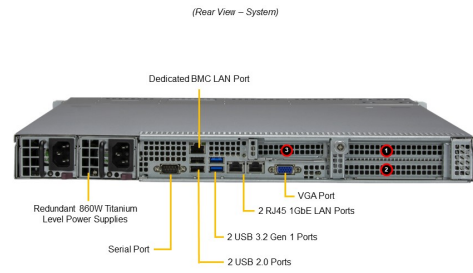


Form Factor	1U Enclosure: 437 x 43 x 597mm (17.2" x 1.7" x 23.5") Package: 597 x 197 x 800mm (23.5" x 7.75" x 31.5")
Processor	Single Socket E (LGA-4677) 5th Gen Intel® Xeon®/4th Gen Intel® Xeon® Scalable processors Up to 52C/104T; Up to 300MB Cache
GPU	Max GPU Count: Up to 1 double-width or 2 single-width GPUs Supported GPU: NVIDIA PCIe: A2, L4, T400 CPU-GPU Interconnect: PCIe 5.0 x16 CPU-to-GPU Interconnect
System Memory	Slot Count: 8 DIMM slots/8 Channels Max Memory (1DPC): Up to 2TB 5600MT/s ECC DDR5 RDIMM
Drive Bays Configuration	Default: Total 10 bays • 10 front hot-swap 2.5" NVMe*/SAS*/SATA drive bays (*NVMe/SAS support may require additional storage controller and/or cables, please see the optional parts list for details) M.2: 1 M.2 PCIe 3.0 x2 NVMe slot (M-key 2280/22110)
Expansion Slots	Default • 2 PCIe 5.0 x16 FHFL slots • 1 PCIe 5.0 x8 (in x16) LP slot
On-Board Devices	SATA: SATA (6Gbps) ; RAID 0/1/5/10 support NVMe: NVMe; RAID 0/1/5/10 support(Intel® VROC RAID key required) Network Connectivity: 2 RJ45 1GbE with Intel® I210
Input / Output	LAN: 2 RJ45 1 GbE LAN ports 1 RJ45 1 GbE Dedicated BMC LAN port (IPMI shared on LAN port 1) USB: 2 USB 3.2 Gen1 Type-A ports(rear) 2 USB 2.0 Type-A ports(rear) 2 USB 3.2 Gen1 Type-A ports(front) 1 USB 2.0 Type-A port(Header) Video: 1 VGA port Serial: 1 COM port(Rear) 1 COM port(Header) TPM: 1 TPM header



Drive Bay	Description
1 - 6	2.5" Hot-swap PCIe 5.0 NVMe/SAS3/SATA3 Drive Bays

\* NVMe or SAS3 support requires additional parts from the optional parts list



Slot	Slot Description
1	PCIe 5.0 x16 FHFL
2	PCIe 5.0 x16 FHFL
3	PCIe 5.0 x8 (in x16) LP

System Cooling	Fans: Up to 5 middle cooling PWM 40x40x56mm Fan(s) Up to 1 AOC cooling Fan(s) (optional) Air Shroud: 1 Air Shroud
Power Supply	2x 860W Redundant (1 + 1) Titanium Level (96%) power supplies
System BIOS	BIOS Type: AMI 32MB SPI Flash EEPROM
Management	SuperCloud Composer® (SCC); Supermicro Server Manager (SSM); Supermicro Update Manager (SUM); Supermicro SuperDoctor® 5 (SD5); Super Diagnostics Offline (SDO); Supermicro Thin-Agent Service (TAS); SuperServer Automation Assistant (SAA) New!
PC Health Monitoring	CPU: 8 Phase-switching voltage regulator Monitors for CPU Cores, Chipset Voltages, Memory FAN: Fans with tachometer monitoring Pulse Width Modulated (PWM) fan connectors Status monitor for speed control Temperature: Monitoring for CPU and chassis environment Thermal Control for fan connectors
Dimensions and Weight	Weight: Gross Weight: 33.5 lbs (15.2 kg) Net Weight: 21 lbs (9.53 kg) Available Color: Black
Operating Environment	Operating Temperature: 10°C to 35°C (50°F to 95°F) Non-operating Temperature: -30°C to 60°C (-22°F to 140°F) Operating Relative Humidity: 8% to 80% (non-condensing) Non-operating Relative Humidity: 8% to 90% (non-condensing)
Motherboard	<a href="#"><u>Super X13SEW-F</u></a>
Chassis	<a href="#"><u>CSE-116BTS-R000WNP</u></a>